

**Amendments to the Claims:**

Please cancel claim 59 without prejudice, and please amend claims 60-64, 67, 68, 75 and 78 as follows:

1-59. (Cancelled)

60. (Currently Amended) The method of claim ~~59-63~~ wherein removing material from the second surface includes etching grooves in the second surface.

61. (Currently Amended) The method of claim ~~5963~~, further comprising disposing a thermal conductor within at least some of the recesses formed by removing material from the second surface.

62. (Currently Amended) The method of claim ~~5963~~, further comprising coupling an enclosure member to the second surface.

63. (Currently Amended) ~~The method of claim 59, further comprising A method of making a microelectronic device, comprising:~~

~~forming active devices at least proximate to a first surface of a microelectronic substrate, the microelectronic substrate having a second surface facing opposite the first surface, the second surface having a projected area; removing material from the second surface of the microelectronic substrate to form heat transfer surface features, wherein a surface area of the second surface including the heat transfer surface features is greater than the projected area; and coupling to the second surface of the microelectronic substrate an external surface of a sealed heat transport system having a sealed cavity and a thermal conductor disposed within the cavity.~~

64. (Currently Amended) A method of making a microelectronic device, comprising: forming active devices at least proximate to a first surface of a microelectronic substrate;

forming at least one recess in a second surface of the microelectronic substrate facing opposite from the first surface;  
disposing a thermal conductor in the at least one recess, wherein the thermal conductor is not configured to provide electrical communication between the microelectronic substrate and external components; and  
coupling an enclosure member to the second surface of the microelectronic substrate to sealably encloseing the at least one recess with the thermal conductor positioned and configured to transfer heat from the active devices to a region external to the microelectronic substrate.

65. (Original) The method of claim 64 wherein forming at least one recess includes etching at least one groove.

66. (Original) The method of claim 64 wherein forming at least one recess includes forming a plurality of grooves.

67. (Currently Amended) The method of claim 64 wherein disposing a thermal conductor includes placing a liquid in a position to absorb heat from the microelectronic substrate, vaporize, transfer heat to ~~an~~the enclosure member, and condense.

68. (Currently Amended) A method of making a microelectronic device, comprising:  
forming active devices at least proximate to a first surface of a microelectronic substrate, the microelectronic substrate having a second surface facing opposite from the first surface, the second surface having a projected area;  
forming heat transfer surface features integrally in the second surface of the microelectronic substrate, wherein a surface area of the second surface including the heat transfer surface features is greater than the projected area; and  
attaching to the second surface of the microelectronic substrate a heat transport system with a thermal conductor configured to transfer heat from the active devices to a

region external to the microelectronic device, the heat transport system being in thermal communication with the heat transfer surface features.

69. (Original) The method of claim 68, wherein the thermal conductor is the second of two thermal conductors, and wherein the method further comprises disposing a first thermal conductor between at least some of the heat transfer surface features on the microelectronic substrate.

70. (Original) The method of claim 68 wherein forming heat transfer surface features includes forming a plurality of projections.

71. (Original) The method of claim 68 wherein attaching to the microelectronic substrate a heat transport system includes adhering the heat transport system to the microelectronic substrate with a nitride adhesive.

72-74. (Cancelled)

75. (Currently Amended) The method of claim 59-63 wherein removing material from the second surface comprises forming heat transfer surface features that extend a distance approximately equal to one-third to one-half of a distance between the first and second surfaces of the microelectronic substrate.

76. (Previously Presented) The method of claim 64 wherein:  
forming at least one recess comprises forming a plurality of recesses; and  
sealably enclosing the recesses comprises sealably enclosing the recesses such that the recesses are in fluid communication with each other.

77. (Previously Presented) The method of claim 64 wherein disposing the thermal conductor comprises disposing a fluid in the at least one recess.

78. (Currently Amended) The method of claim 68 wherein attaching the heat transport system comprises attaching ~~the-a sealed~~ heat transport system to the second surface of the microelectronic substrate.

79. (Previously Presented) The method of claim 68 wherein the thermal conductor is a liquid, and wherein attaching the microelectronic substrate comprises positioning the liquid to absorb heat from the microelectronic substrate, vaporize, transfer heat to the region external to the microelectronic device, and condense.

80. (Previously Presented) The method of claim 68 wherein the thermal conductor is not configured to provide electrical communication between the microelectronic substrate and external components.